


**PATENT APPLICATION**

Sheet 1 of 2

<b>FORM PTO-1449</b>  <b>LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT</b>  (Use several sheets if necessary)	<b>ATTY. DOCKET NO.</b> <b>10970792-4</b>	<b>APPLICATION NO.</b>	<b>CONFIRMATION NO.</b>
	<b>APPLICANT</b> <b>Melissa D. Boyd et al.</b>		
	<b>FILING DATE</b> <b>H rewith</b>	<b>GROUP</b> <b>unkn.</b>	

**REFERENCE DESIGNATION**


**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
	1A	4,917,286	04/1990	Pollacek	
	1B	5,016,023	05/1991	Chan et al.	
	1C	5,489,930	02/1996	Anderson	
	1D	5,808,635	09/1998	Kneezel et al.	
	1E	5,939,206	08/1999	Kneezel et al.	
	1F	6,123,410	09/2000	Beerling et al.	
	1G	6,322,206	11/2001	Boyd et al.	
	1H	5,565,900	10/1996	Cowger et al.	
	1I	6,343,857	02/2002	Cowger	
	1J	4,380,770	04/1983	Maruyama	
	1K	5,087,930	02/1992	Roy et al.	

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	PUBLICATION DATE	NAME OF PATENTEE OR APPLICANT	Pages/Columns/Lines Where Relevant Passages/Figures Appear	Check if Translation attached
	1L					
	1M					
	1N					
	1O					
	1P					

**OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)**

	1Q	"Precision Flip-Chip Solder Bump Interconnects For Optical Packaging"; William R. Imler et al.; December 1992; IEEE; Vol. 15; No. 6; pgs: 977-982.
	1R	"Use Of AuSn Solder Bumps In Three-Dimensional Passive Aligned Packaging of LD/PD Arrays On Si Optical Benches"; Masataka Itoh, et al; 1996; IEEE; pgs: 1-7.
	1S	"Active Atmosphere Solder Self-Alignment And Bonding Of Optitcal Components"; R.D. Eshmukh et al.; Vol. 16; No. 2; Second Quarter 1993; International Journal Of Microcircuits And Electronics Packaging; pgs: 97-107.

EXAMINER

DATE CONSIDERED

9/13/04

## PATENT APPLICATION

Sheet 2 of 2

FORM PTO-1449

LIST OF PATENTS AND PUBLICATIONS FOR  
APPLICANT'S INFORMATION DISCLOSURE  
STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.

10970792-4

APPLICATION NO.

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Melissa D. Boyd et al.

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## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
	2A	5,097,275	03/1992	Takita	
	2B	5,561,448	10/1996	Kaneko et al.	
	2C				
	2D				
	2E				
	2F				
	2G				
	2H				
	2I				
	2J				
	2K				

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	2L					
	2M					
	2N					
	2O					
	2P					

## OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

	2Q	"Multilayered Focal Plane Structures With Self-Aligning Detector Assembly"; David E. Ludwig; SPIE; Vol. 2745; 1996; pgs: 149-158.
	2R	"Experimental Results On The Self-Alignment Process Using Au/Sn Metallurgy And On The Growth Of The S-Phase During The Reflow"; Christine Kallmayer, et al; 1995; Semiconductor Technology Center, Inc-Symposium; pgs 225-237.
	2S	"Photolithography In Anisotropically Etched Grooves"; S. Linder, et al.; 1996; IEEE; pgs. 38-43.

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